

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) An imaging apparatus comprising:

an imaging portion in which a cover glass is adhered to an imaging surface side of a solid-state image pickup device as if sandwiching leads, a slight first air gap is formed between the cover glass and the imaging surface of the solid-state image pickup device and a circumference of the cover glass is larger than the solid-state image pickup device, and

a circuit board having an accommodation concave portion for accommodating the solid-state image pickup device so as to connect the leads to terminals on an upper edge of the accommodation concave portion,

wherein the concave portion forms a second air gap clearance between a first adhesion area and a second adhesion area, and the second air gap is formed between the solid-state image pickup device and the circuit board in the concave portion, and the first air gap and the second air gap are airtight spaces respectively, the first adhesion area being between the solid state image sensor and the cover glass, and the second adhesion area being between the cover glass and the circuit board, wherein the first adhesion area and the second adhesion area are on a same side of the cover glass, and wherein said cover glass is formed in a size for blocking an entrance of said accommodation concave portion;

wherein the adhesion area between the cover glass and the circuit board adheres to the circuit board in a state of sealing the accommodation concave portion.

- 2-5. (Canceled)

6. (New) The imaging apparatus according to claim 1, wherein

said first adhesion is between an edge of the solid state image sensor and the cover glass,

the second adhesion area is between the cover glass and an edge of the circuit board which is adjacent to said edge of the solid state image sensor, and

the clearance is formed between said edge of the solid state image sensor and said edge of the circuit board.